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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c56-hsi-so

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# PIC16C5X

### 8-Bit EPROM/ROM-Based CMOS Microcontrollers

### 1.0 GENERAL DESCRIPTION

The PIC16C5X from Microchip Technology is a family of low cost, high performance, 8-bit fully static, EPROM/ROM-based CMOS microcontrollers. It employs a RISC architecture with only 33 single word/ single cycle instructions. All instructions are single cycle except for program branches which take two cycles. The PIC16C5X delivers performance in an order of magnitude higher than its competitors in the same price category. The 12-bit wide instructions are highly symmetrical resulting in 2:1 code compression over other 8-bit microcontrollers in its class. The easy to use and easy to remember instruction set reduces development time significantly.

The PIC16C5X products are equipped with special features that reduce system cost and power requirements. The Power-on Reset (POR) and Device Reset Timer (DRT) eliminate the need for external RESET circuitry. There are four oscillator configurations to choose from, including the power saving LP (Low Power) oscillator and cost saving RC oscillator. Power saving SLEEP mode, Watchdog Timer and Code Protection features improve system cost, power and reliability.

The UV erasable CERDIP packaged versions are ideal for code development, while the cost effective One Time Programmable (OTP) versions are suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in OTP microcontrollers, while benefiting from the OTP's flexibility.

The PIC16C5X products are supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a low cost development programmer and a full featured programmer. All the tools are supported on IBM<sup>®</sup> PC and compatible machines.

### 1.1 Applications

The PIC16C5X series fits perfectly in applications ranging from high speed automotive and appliance motor control to low power remote transmitters/receivers, pointing devices and telecom processors. The EPROM technology makes customizing application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make this microcontroller series perfect for applications with space limitations. Low cost, low power, high performance ease of use and I/O flexibility make the PIC16C5X series very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, replacement of "glue" logic in larger systems, co-processor applications).

		Pin Number		Pin Buffer	Buffer	Description
Pin Name	DIP	SOIC	SSOP	Туре	Туре	Description
RA0	6	6	5	I/O	TTL	Bi-directional I/O port
RA1	7	7	6	I/O	TTL	
RA2	8	8	7	I/O	TTL	
RA3	9	9	8	I/O	TTL	
RB0	10	10	9	I/O	TTL	Bi-directional I/O port
RB1	11	11	10	I/O	TTL	
RB2	12	12	11	I/O	TTL	
RB3	13	13	12	I/O	TTL	
RB4	14	14	13	I/O	TTL	
RB5	15	15	15	I/O	TTL	
RB6	16	16	16	I/O	TTL	
RB7	17	17	17	I/O	TTL	
RC0	18	18	18	I/O	TTL	Bi-directional I/O port
RC1	19	19	19	I/O	TTL	
RC2	20	20	20	I/O	TTL	
RC3	21	21	21	I/O	TTL	
RC4	22	22	22	I/O	TTL	
RC5	23	23	23	I/O	TTL	
RC6	24	24	24	I/O	TTL	
RC7	25	25	25	I/O	TTL	
TOCKI	1	1	2	Ι	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
MCLR	28	28	28	I	ST	Master clear (RESET) input. This pin is an active low RESET to the device.
OSC1/CLKIN	27	27	27	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	26	26	26	0	_	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
Vdd	2	2	3,4	Р	_	Positive supply for logic and I/O pins.
Vss	4	4	1,14	Р		Ground reference for logic and I/O pins.
N/C	3,5	3,5		_		Unused, do not connect.

### TABLE 3-2: PINOUT DESCRIPTION - PIC16C55, PIC16C57, PIC16CR57

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

NOTES:

### 4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A welldesigned crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k $\Omega$  resistor provides the negative feedback for stability. The 10 k $\Omega$  potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k $\Omega$  resistors provide the negative feedback to bias the inverters in their linear region.



### 5.0 RESET

PIC16C5X devices may be RESET in one of the following ways:

- Power-On Reset (POR)
- MCLR Reset (normal operation)
- MCLR Wake-up Reset (from SLEEP)
- WDT Reset (normal operation)
- WDT Wake-up Reset (from SLEEP)

Table 5-1 shows these RESET conditions for the PCL and STATUS registers.

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-On Reset (POR), MCLR or WDT Reset. A MCLR or WDT wake-up from SLEEP also results in a device RESET, and not a continuation of operation before SLEEP. The  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  bits (STATUS <4:3>) are set or cleared depending on the different RESET conditions (Table 5-1). These bits may be used to determine the nature of the RESET.

Table 5-3 lists a full description of RESET states of all registers. Figure 5-1 shows a simplified block diagram of the On-chip Reset circuit.

### TABLE 5-1: STATUS BITS AND THEIR SIGNIFICANCE

Condition	ТО	PD
Power-On Reset	1	1
MCLR Reset (normal operation)	u	u
MCLR Wake-up (from SLEEP)	1	0
WDT Reset (normal operation)	0	1
WDT Wake-up (from SLEEP)	0	0

Legend: u = unchanged, x = unknown, - = unimplemented read as '0'.

### TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH RESET

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	<u>Value</u> on MCLR and WDT Reset
03h	STATUS	PA2	PA1	PA0	TO	PD	Z	DC	С	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, q = see Table 5-1 for possible values.

### 8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

### 8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device. When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for TOCKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on TOCKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

### 8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.



Belay from clock input change to Timer0 increment is 3 lose to 7 lose (duration of Q = lose). There the error in measuring the interval between two edges on Timer0 input = ± 4 Tose max.

### 8.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer (WDT), respectively (Section 9.2.1). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x, etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a RESET, the prescaler contains all '0's.

### 8.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on the fly" during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 8-1) must be executed when changing the prescaler assignment from Timer0 to the WDT.

### EXAMPLE 8-1: CHANGING PRESCALER (TIMER0→WDT)

CLRWDT	;Clear WDT
CLRF TMR0	Clear TMR0 & Prescaler
MOVLW B'00xx1111'	;Last 3 instructions in
	this example
OPTION	;are required only if
	;desired
CLRWDT	;PS<2:0> are 000 or
	;001
MOVLW B'00xx1xxx'	;Set Prescaler to
OPTION	;desired WDT rate

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 8-2. This sequence must be used even if the WDT is disabled. A CLRWDT instruction should be executed before switching the prescaler.

### EXAMPLE 8-2: CHANGING PRESCALER (WDT $\rightarrow$ TIMER0)

CLRWDT		;Clear WDT and
		;prescaler
MOVLW	B'xxxx0xxx'	;Select TMR0, new
		;prescale value and
		;clock source

OPTION

NOTES:

GOTO	Unconditional Branch						
Syntax:	[ label ]	GOTO	k				
Operands:	$0 \le k \le 511$						
Operation:	$k \rightarrow PC < 8:0>;$ STATUS <6:5> $\rightarrow PC < 10:9>$						
Status Affected:	None						
Encoding:	101k	kkkk	kkkk				
Description:	GOTO is an unconditional branch. The 9-bit immediate value is loaded into PC bits <8:0>. The upper bits of PC are loaded from STATUS<6:5>. GOTO is a two- cycle instruction.						
Words:	1						
Cycles:	2						
Example:	GOTO THERE						
After Instruct PC =	ion address	G (THER	E)				

INCF	Increment f				
Syntax:	[label] INCF f,d				
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d  \in  [0,1] \end{array}$				
Operation:	(f) + 1 $\rightarrow$ (dest)				
Status Affected:	Z				
Encoding:	0010 10df ffff				
Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.				
Words:	1				
Cycles:	1				
Example:	INCF CNT, 1				
Before Instru CNT Z After Instruct CNT Z	= 0xFF = 0				

INCFSZ	Increment f, Skip if 0				
Syntax:	[label] INCFSZ f,d				
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in [0,1] \end{array}$				
Operation:	(f) + 1 $\rightarrow$ (dest), skip if result = 0				
Status Affected:	None				
Encoding:	0011 11df ffff				
Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, then the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two- cycle instruction.				
Words:	1				
Cycles:	1(2)				
Example:	HERE INCFSZ CNT, 1 GOTO LOOP CONTINUE • • •				
Before Instru PC After Instruc	= address (HERE)				
CNT if CNT PC if CNT PC	<pre>= CNT + 1; = 0, = address (CONTINUE); ≠ 0, = address (HERE +1)</pre>				

MOVWF	Move W to f					
Syntax:	[ <i>label</i> ] MOVWF f					
Operands:	$0 \leq f \leq 31$					
Operation:	$(W) \rightarrow (f)$					
Status Affected:	None					
Encoding:	0000 001f ffff					
Description:	Move data from the W register to					
	register 'f'.					
Words:	1					
Cycles:	1					
Example:	MOVWF TEMP_REG					
W After Instruct	REG = 0xFF $= 0x4F$					

NOP	No Operation				
Syntax:	[ label ]	NOP			
Operands:	None				
Operation:	No operation				
Status Affected:	None				
Encoding:	0000	0000	0000		
Description:	No opera	ation.			
Words:	1				
Cycles:	1				
Example:	NOP				

OPTION	Load Ol		egister			
Syntax:	[ label ]	OPTIO	N			
Operands:	None					
Operation:	$(W) \rightarrow C$	PTION				
Status Affected:	None					
Encoding:	0000	0000	0010			
Description:		The content of the W register is loaded into the OPTION register.				
Words:	1					
Cycles:	1					
Example	OPTION					
Before Instru	ction					
W	•	07				
After Instructi						
OPTION	= 0x	07				

RETLW	Return with Literal in W
Syntax:	[ <i>label</i> ] RETLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k \rightarrow (W);$ TOS $\rightarrow$ PC
Status Affected:	None
Encoding:	1000 kkkk kkkk
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example:	CALL TABLE ;W contains ;table offset ;value. • ;W now has table • ;value.
TABLE	<pre>ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ;</pre>
Before Instru	
W After Instruct	= 0x07
After Instruct W	= value of k8

SUBWF	Subti	ract W	/ from f
Syntax:	[label	] SU	JBWF f,d
Operands:	$0 \le f \le$	≤ 31	
	d ∈ [0	),1]	
Operation:	(f) – (	W) $\rightarrow$	(dest)
Status Affected:	C, DC	C, Z	
Encoding:	000	0 10	Odf ffff
Description:	the W is 0 th regist	/ regist ne resu er. If 'c	's complement method) ter from register 'f'. If 'd' ult is stored in the W d' is 1 the result is c in register 'f'.
Words:	1		
Cycles:	1		
Example 1:	SUBW	FR	REG1, 1
Before Instruct REG1 W C After Instruct REG1 W C Example 2: Before Instruct REG1 W C After Instruct REG1 W C Example 3: Before Ins REG1 W C After Instruct REG1	= = = = = ion = = truction = = = =	1 2 ? 0xFF	; result is positive ; result is zero
W C	= =	2 0	; result is negative
-		-	,

SWAPF	Swap Nibbles in f
Syntax:	[label] SWAPF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d  \in  [0,1] \end{array}$
Operation:	$(f<3:0>) \rightarrow (dest<7:4>);$ $(f<7:4>) \rightarrow (dest<3:0>)$
Status Affected:	None
Encoding:	0011 10df ffff
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.
Words:	1
Cycles:	1
Example	SWAPF REG1, 0
REG1 After Instruct REG1 W	= 0xA5 ion = 0xA5 = 0x5A
TRIS	Load TRIS Register
Syntax:	[ <i>label</i> ] TRIS f
Operands:	f = 5, 6 or 7
Operation:	(W) $\rightarrow$ TRIS register f
Status Affected:	None
Encoding:	0000 0000 0fff
Description:	TRIS register 'f' ( $f = 5, 6, or 7$ ) is loaded with the contents of the W register.
Words:	1
Cycles:	1
Example	TRIS PORTB
Before Instru W After Instructi TRISB	= 0xA5 on



### FIGURE 12-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING -PIC16C54/55/56/57

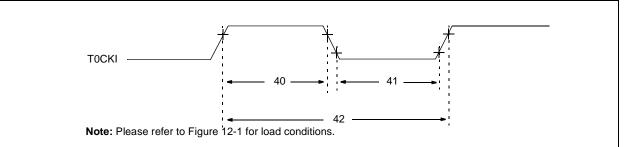
### TABLE 12-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C54/55/56/57

AC Chara	cteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended						
Param No.	Symbol	Characteristic Min Typ† Max Units Conditions						
30	TmcL	MCLR Pulse Width (low)	100*	—	—	ns	VDD = 5.0V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
34	Tioz	I/O Hi-impedance from MCLR Low	_	_	100*	ns		

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

### FIGURE 12-5: TIMER0 CLOCK TIMINGS - PIC16C54/55/56/57



### TABLE 12-4: TIMER0 CLOCK REQUIREMENTS - PIC16C54/55/56/57

AC Ch	AC CharacteristicsStandard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended									
Param No.	Symbol	Symbol Characteristic Min Typ†				Units	Conditions			
40	Tt0H	T0CKI High Pulse Width - No Prescaler - With Prescaler	0.5 Tcy + 20* 10*			ns ns				
41	TtOL	TOCKI Low Pulse Width - No Prescaler - With Prescaler	0.5 TCY + 20* 10*		_	ns				
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N		—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)			

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

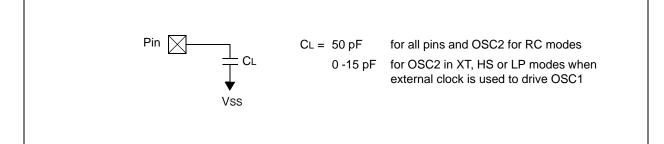
### 13.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS

2. Tp	pS	
Т		
F	Frequency	T Time
Lowe	ercase letters (pp) and their meanings:	
рр		
2	to	mc MCLR
ck	CLKOUT	osc oscillator
су	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer
Uppe	ercase letters and their meanings:	
S		
F	Fall	P Period
Н	High	R Rise
I	Invalid (Hi-impedance)	V Valid
L	Low	Z Hi-impedance

### FIGURE 13-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16CR54A



## PIC16C5X









### 15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

		FICTULCJ	-7 0-		cnac	ч)				
	PIC16LC54A-04E (Extended)				$\begin{array}{llllllllllllllllllllllllllllllllllll$					
PIC16C (Extend		10E, 20E	$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Param No.	Symbol	Characteristic	Min	Max	Units	Conditions				
	Vdd	Supply Voltage			•					
D001		PIC16LC54A	3.0 2.5	_	6.25 6.25	V V	XT and RC modes LP mode			
D001A		PIC16C54A	3.5 4.5		5.5 5.5	V V	RC and XT modes HS mode			
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>	_	1.5*		V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	-	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_		V/ms	See Section 5.1 for details on Power-on Reset			
	Idd	Supply Current <sup>(2)</sup>	•		•					
D010		PIC16LC54A	—	0.5	25	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes			
			—	11	27	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Commercial			
			—	11	35	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Industrial			
			_	11	37	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Extended			
D010A		PIC16C54A	—	1.8	3.3	mA	Fosc = 4.0 MHz, VDD = 5.5V, $RC^{(3)}$ and XT modes			
			—	4.8	10	mA	Fosc = 10 MHz, VDD = 5.5V, HS mode			
			—	9.0	20	mA	Fosc = 20 MHz, VDD = 5.5V, HS mode			

Legend: Rows with standard voltage device data only are shaded for improved readability.

- \* These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

### 17.1 DC Characteristics:PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC PIC16LC (Comm	-	ustrial)	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$						
PIC16C5X PIC16CR5X (Commercial, Industrial)				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}\mbox{C} \leq \mbox{TA} \leq +70^{\circ}\mbox{C} \mbox{ for commercial} \\ -40^{\circ}\mbox{C} \leq \mbox{TA} \leq +85^{\circ}\mbox{C for industrial} \end{array}$					
Param No. Symbol Characteristic/Device				Тур†	Max	Units	Conditions		
	IPD	Power-down Current <sup>(2)</sup>							
D020		PIC16LC5X		0.25 0.25 1 1.25	2 3 5 8	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled, Commercial $VDD = 2.5V$ , WDT disabled, Industrial $VDD = 2.5V$ , WDT enabled, Commercial $VDD = 2.5V$ , WDT enabled, Industrial		
D020A		PIC16C5X		0.25 0.25 1.8 2.0 4 4 9.8 12	4.0 5.0 7.0* 8.0* 12* 14* 27* 30*	μΑ μΑ μΑ μΑ μΑ μΑ μΑ μΑ	VDD = 3.0V, WDT disabled, Commercial VDD = 3.0V, WDT disabled, Industrial VDD = 5.5V, WDT disabled, Industrial VDD = 5.5V, WDT disabled, Industrial VDD = 3.0V, WDT enabled, Commercial VDD = 3.0V, WDT enabled, Industrial VDD = 5.5V, WDT enabled, Commercial VDD = 5.5V, WDT enabled, Industrial		

Legend: Rows with standard voltage device data only are shaded for improved readability.

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

**3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .



### FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

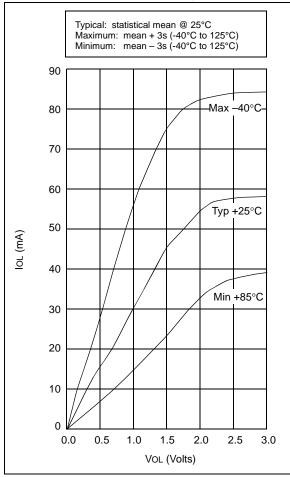
### TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

AC Charac	teristics	Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial)Operating Voltage VDD range is described in Section 19.1.							
Param No.	Symbol	Characteristic Min Typ† Max Units Condit							
30	TmcL	MCLR Pulse Width (low)	1000*	_	_	ns	VDD = 5.0V		
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)		
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)		
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns			

\* These parameters are characterized but not tested.

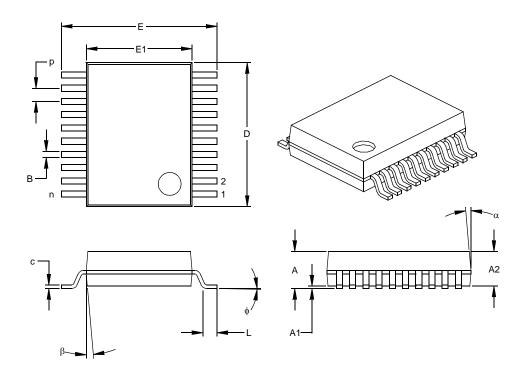
† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

### FIGURE 20-9: IOL vs. VOL, VDD = 5 V



### 20-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units INCHES*						MILLIMETERS			
Dimensio	MIN	NOM	MAX	MIN	NOM	MAX				
Number of Pins	n		20			20				
Pitch	р		.026			0.65				
Overall Height	Α	.068	.073	.078	1.73	1.85	1.98			
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83			
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25			
Overall Width	Е	.299	.309	.322	7.59	7.85	8.18			
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38			
Overall Length	D	.278	.284	.289	7.06	7.20	7.34			
Foot Length	L	.022	.030	.037	0.56	0.75	0.94			
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25			
Foot Angle	ф	0	4	8	0.00	101.60	203.20			
Lead Width	В	.010	.013	.015	0.25	0.32	0.38			
Mold Draft Angle Top	α	0	5	10	0	5	10			
Mold Draft Angle Bottom	β	0	5	10	0	5	10			

\* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-150 Drawing No. C04-072